

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6957134

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
JIN WOOK HUH	09/03/2021
KI RIM LEE	09/03/2021
RECEIVING PARTY DATA	
Name:	HANWHA TECHWIN CO., LTD.
Street Address:	6, PANGYO-RO 319BEON-GIL, BUNDANG-GU
City:	SEONGNAM-SI, GYEONGGI-DO
State/Country:	KOREA, REPUBLIC OF
Postal Code:	13488
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17495975
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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ATTORNEY DOCKET NUMBER:	HT71003
NAME OF SUBMITTER:	JASON Y. PAHNG
SIGNATURE:	/Jason Y. Pahng/
DATE SIGNED:	10/07/2021
Total Attachments: 2	
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ASSIGNMENT OF PATENT APPLICATION

WHEREAS, I/We, HUH, Jin Wook, a citizen of Republic of Korea, residing at 6, Pangyo-ro 319beon-gil, Bundang-gu, Seongnam-si, Gyeonggi-do 13488, Republic of Korea, and LEE, Ki Rim, a citizen of Republic of Korea, residing at 6, Pangyo-ro 319beon-gil, Bundang-gu, Seongnam-si, Gyeonggi-do 13488, Republic of Korea ASSIGNOR(S), am/are the inventor(s) of an invention in:

THERMAL CAMERA AND METHOD OF PROCESSING THERMAL IMAGE THEREOF

for which I/we have executed an application for Letters Patent of the United States,

(Check One) on _____ ;
 U.S. Serial Number _____ filed on _____ ;
 International Application No. _____ filed on _____ ;

PRIOR FOREIGN APPLICATION(S)

Priority Claimed

10-2021-0060340 Rep. of Korea May 10, 2021 Yes: V No: _____
(Number) (Country) (Day/Month/Year)

and

WHEREAS, HANWHA TECHWIN CO., LTD., a Korean corporation of 6, Pangyo-ro 319beon-gil, Bundang-gu, Seongnam-si, Gyeonggi-do 13488, Republic of Korea, ASSIGNEES, are desirous of obtaining the entire right, title and interest in, to and under the said invention and the said application;

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to me/us in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, I/we, the said ASSIGNOR(S) have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title and interest in, to and under the said invention, and the said application and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reexamination certificates, reissues and extensions thereof, and I/we hereby authorize and request the Commissioner of Patents of the United States, to issue all Letters Patent for said invention to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I/WE HEREBY covenant that I/we have the full right to convey the entire interest herein assigned, and that I/we have not executed, and will not execute, any agreement in conflict herewith.

AND I/WE HEREBY further covenant and agree that I/we will communicate to said ASSIGNEE, its successor s, legal representatives and assigns, any facts known to me/us respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and general

y do everything possible to aid the said *ASSIGNEE*, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention at the expense of the *ASSIGNEES*.

IN TESTIMONY WHEREOF, I/we hereunto set my/our hand(s) and seal(s) the day and year set opposite my/our signature(s).

HUH, Jin Wook Jin Wook Huh Date September 3, 2021
Inventor Signature

LEE, Ki Rim Ki Rim Lee Date September 3, 2021
Inventor Signature